

EMS11HJF-3.125M

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REGULATORY COMPLIANCE (Data Sheet downloaded on Dec 8, 2019)


[Click badges to download compliance docs](#)

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ITEM DESCRIPTION

Spread Spectrum MEMS Clock Oscillators LVCMOS (CMOS) 1.8Vdc 4 Pad 5.0mm x 7.0mm Plastic Surface Mount (SMD) 3.125MHz ± 50 ppm Maximum over -40°C to $+85^{\circ}\text{C}$ Power Down (Disabled Output Logic Low) -2.00% Down Spread

ELECTRICAL SPECIFICATIONS

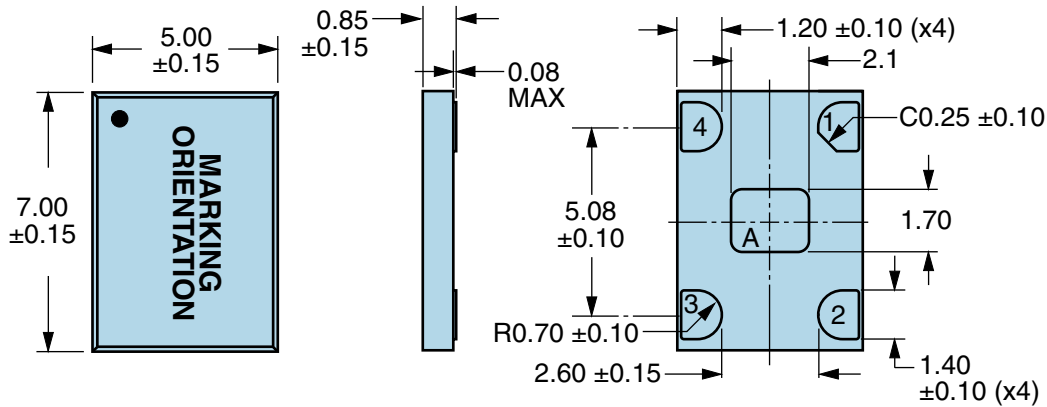
Nominal Frequency	3.125MHz
Frequency Tolerance/Stability	± 50 ppm Maximum over -40°C to $+85^{\circ}\text{C}$ (Inclusive of all conditions: Calibration Tolerance at 25°C , Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C , 260°C Reflow, Shock, and Vibration)
Aging at 25°C	± 1 ppm Maximum First Year
Supply Voltage	1.8Vdc $\pm 5\%$
Maximum Supply Voltage	-0.5Vdc to $+1.98\text{Vdc}$
Input Current	25mA Maximum (Unloaded; Nominal Vdd)
Output Voltage Logic High (Voh)	90% of Vdd Minimum (IOH= -8mA)
Output Voltage Logic Low (Vol)	10% of Vdd Maximum (IOL= $+8\text{mA}$)
Rise/Fall Time	2nSec Maximum (Measured from 20% to 80% of waveform)
Duty Cycle	50 ± 5 (%) (Measured at 50% of waveform)
Load Drive Capability	15pF Maximum
Output Logic Type	CMOS
Output Control Function	Power Down (Disabled Output Logic Low)
Power Down Input Voltage (Vih and Vil)	70% of Vdd Minimum or No Connection to Enable Output, 30% of Vdd Maximum to Disable Output
Standby Current	50 μA Maximum (Disabled Output: Logic Low) (Pad 1=Ground)
Spread Spectrum	-2.00% Down Spread
Modulation Frequency	30kHz Minimum, 32kHz Typical, 35kHz Maximum
Period Jitter	90pSec Maximum (Cycle to Cycle; Spread Spectrum-On; Fo=133.333M, Vdd=1.8Vdc)
Start Up Time	10mSec Maximum
Storage Temperature Range	-55°C to $+125^{\circ}\text{C}$

ENVIRONMENTAL & MECHANICAL SPECIFICATIONS

ESD Susceptibility	MIL-STD-883, Method 3015, Class 2, HBM 2000V
Flammability	UL94-V0
Mechanical Shock	MIL-STD-883, Method 2002, Condition G, 30,000G
Moisture Resistance	MIL-STD-883, Method 1004
Moisture Sensitivity Level	J-STD-020, MSL 1
Resistance to Soldering Heat	MIL-STD-202, Method 210, Condition K
Resistance to Solvents	MIL-STD-202, Method 215
Solderability	MIL-STD-883, Method 2003 (Four I/O Pads on bottom of package only)
Temperature Cycling	MIL-STD-883, Method 1010, Condition B
Thermal Shock	MIL-STD-883, Method 1011, Condition B
Vibration	MIL-STD-883, Method 2007, Condition A, 20G

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MECHANICAL DIMENSIONS (all dimensions in millimeters)



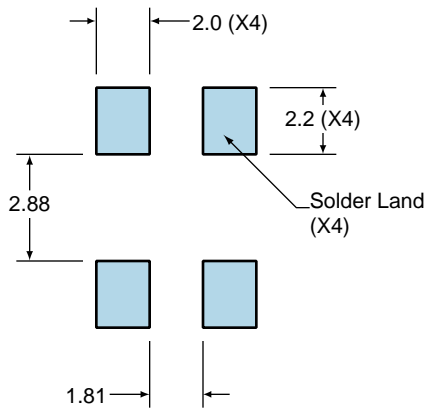
PIN	CONNECTION
1	Power Down (Logic Low)
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	XXXX or XXXXX XXXX or XXXXX=Ecliptek Manufacturing Identifier

Note A: Center paddle is connected internally to oscillator ground (Pad 2).

Suggested Solder Pad Layout

All Dimensions in Millimeters



All Tolerances are ±0.1

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OUTPUT WAVEFORM & TIMING DIAGRAM



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Test Circuit for CMOS Output



Note 1: An external $0.01\mu\text{F}$ ceramic bypass capacitor in parallel with a $0.1\mu\text{F}$ high frequency ceramic bypass capacitor close (less than 2mm) to the package ground and supply voltage pin is required.

Note 2: A low capacitance ($<12\text{pF}$), 10X attenuation factor, high impedance ($>10\text{Mohms}$), and high bandwidth ($>300\text{MHz}$) passive probe is recommended.

Note 3: Capacitance value C_L includes sum of all probe and fixture capacitance.

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Recommended Solder Reflow Methods



High Temperature Infrared/Convection

Ts MAX to Tl (Ramp-up Rate)	3°C/Second Maximum
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Preheat

- Temperature Minimum (Ts MIN)	150°C
- Temperature Typical (Ts TYP)	175°C
- Temperature Maximum (Ts MAX)	200°C
- Time (ts MIN)	60 - 180 Seconds

Ramp-up Rate (Tl to Tp)	3°C/Second Maximum
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Time Maintained Above:

- Temperature (Tl)	217°C
- Time (tL)	60 - 150 Seconds

Peak Temperature (Tp)	260°C Maximum for 10 Seconds Maximum
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Target Peak Temperature (Tp Target)	250°C +0/-5°C
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Time within 5°C of actual peak (tp)	20 - 40 Seconds
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Ramp-down Rate	6°C/Second Maximum
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Time 25°C to Peak Temperature (t)	8 Minutes Maximum
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Moisture Sensitivity Level	Level 1
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Recommended Solder Reflow Methods



Low Temperature Infrared/Convection 240°C

T_s MAX to T_L (Ramp-up Rate)	5°C/Second Maximum
Preheat	
- Temperature Minimum (T_s MIN)	N/A
- Temperature Typical (T_s TYP)	150°C
- Temperature Maximum (T_s MAX)	N/A
- Time (t_s MIN)	60 - 120 Seconds
Ramp-up Rate (T_L to T_P)	5°C/Second Maximum
Time Maintained Above:	
- Temperature (T_L)	150°C
- Time (t_L)	200 Seconds Maximum
Peak Temperature (T_P)	240°C Maximum
Target Peak Temperature (T_P Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
Time within 5°C of actual peak (t_p)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
Ramp-down Rate	5°C/Second Maximum
Time 25°C to Peak Temperature (t)	N/A
Moisture Sensitivity Level	Level 1

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum.

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum.